

30V N-Channel Enhancement Mode MOSFET

V_{DS} = 30V

R_{DS(ON)}, V_{gs}@10V, I_{ds}@12A = 10.5mΩ

R_{DS(ON)}, V_{gs}@4.5V, I_{ds}@12A = 15mΩ

Features

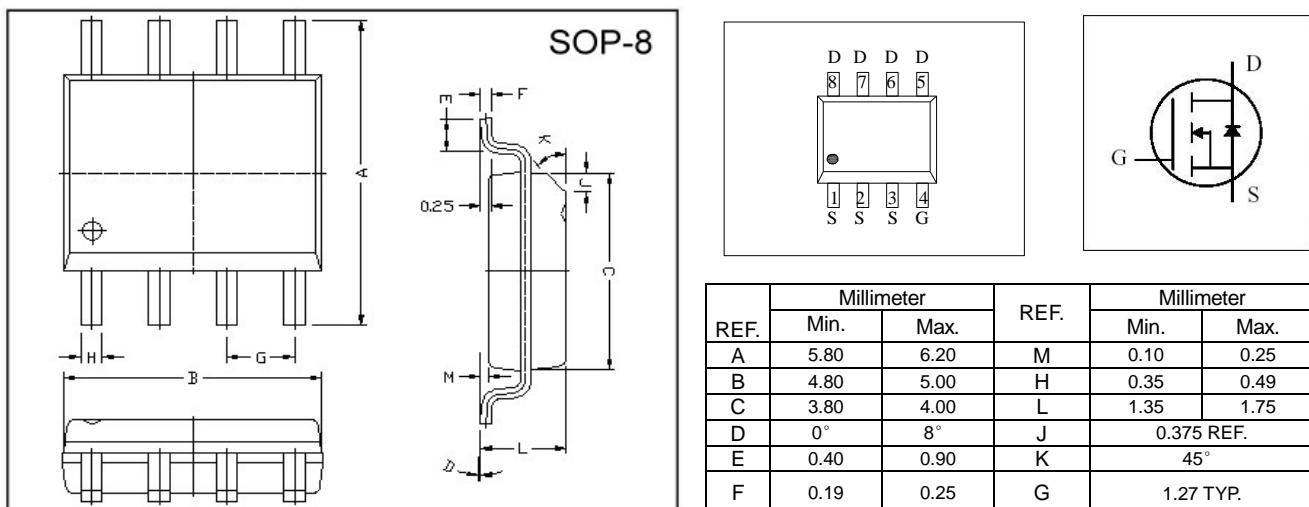
Advanced trench process technology

High Density Cell Design For Ultra Low On-Resistance

Fully Characterized Avalanche Voltage and Current

Improved Shoot-Through FOM

Package Dimensions



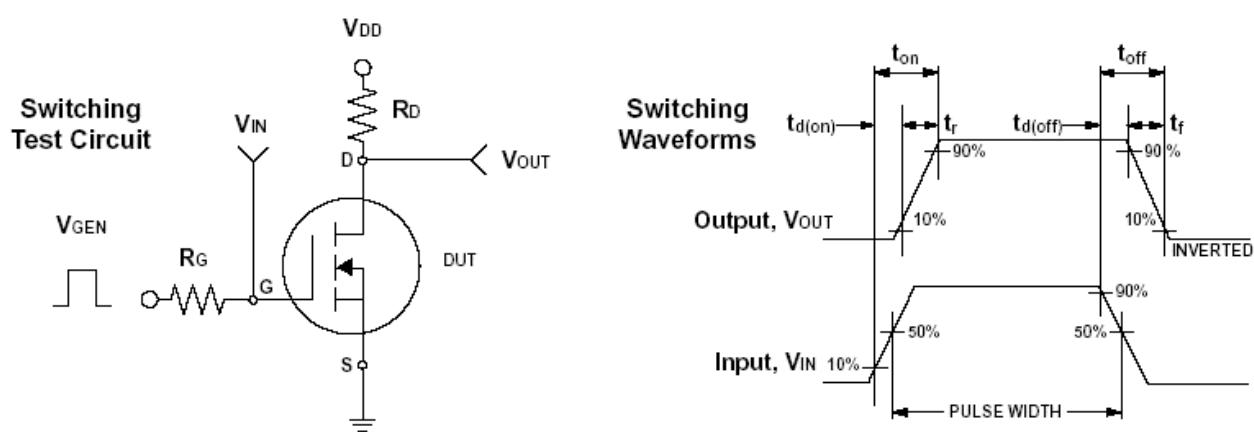
Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	± 20	
Continuous Drain Current	I _D	12	A
Pulsed Drain Current	I _{DM}	48	
Maximum Power Dissipation	P _D	2.5	W
		1.2	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to 150	°C
Avalanche Energy with Single Pulse	EAS	150	mJ
Junction-to-Case Thermal Resistance	R _{θJC}	25	°C/W
Junction-to-Ambient Thermal Resistance (PCB mounted)	R _{θJA}	50	

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ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 12A$		11.0	15.0	$m\Omega$
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 12A$		8.5	10.5	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.8	3	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24V, V_{GS} = 0V$			1	μA
Gate Body Leakage	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
Forward Transconductance	g_f	$V_{DS} = 15V, I_D = 12A$		64	—	S
Dynamic						
Total Gate Charge	Q_g	$V_{DS} = 15V, I_D = 12A$ $V_{GS} = 5V$		12	45	nC
Gate-Source Charge	Q_{gs}			4.5		
Gate-Drain Charge	Q_{gd}			3.6		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15V, R_G = 6\Omega$ $I_D = 1A, V_{GS} = 10V$		22	35	ns
Turn-On Rise Time	t_r			13	20	
Turn-Off Delay Time	$t_{d(off)}$			82	125	
Turn-Off Fall Time	t_f			30	45	
Input Capacitance	C_{iss}	$V_{DS} = 15V, V_{GS} = 0V$ $f = 1.0 \text{ MHz}$		1180		pF
Output Capacitance	C_{oss}			270		
Reverse Transfer Capacitance	C_{rss}			145		
Source-Drain Diode						
Max. Diode Forward Current	I_s				2.0	A
Diode Forward Voltage	V_{SD}	$I_s = 2A, V_{GS} = 0V$			1.5	V

Note: Pulse test: pulse width <= 300us, duty cycle<= 2%



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Typical Characteristics ($T_J = 25^\circ\text{C}$ Noted)
